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Global Low Thermal Expansion Coefficient Electronic Cloth for AI Chip Packaging Supply, Demand and Key Producers, 2026-2032

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Abstracts

The global Low Thermal Expansion Coefficient Electronic Cloth for AI Chip Packaging market size is expected to reach $ 886 million by 2032, rising at a market growth of 6.3% CAGR during the forecast period (2026-2032).

Low Thermal Expansion Coefficient Electronic Cloth for AI Chip Packaging, also referred to as Low-CTE electronic cloth or T-glass fabric in industry terminology, is a specialized high-end electronic-grade glass fiber fabric engineered for advanced semiconductor packaging applications. The material is defined by its coefficient of thermal expansion (CTE), typically maintained below 3 ppm/°C, which is precisely matched to the thermal expansion characteristics of silicon-based chips. This CTE compatibility is critical in AI chip packaging environments, where high-power computing generates significant temperature fluctuations during operation. The low-CTE property effectively mitigates warpage of packaging substrates and prevents solder joint fatigue failure, ensuring long-term interconnection reliability. Beyond thermal management, the material exhibits excellent dimensional stability, high elastic modulus, low dielectric loss, and superior mechanical strength. It serves as an indispensable reinforcement material in IC substrates and packaging substrates for 2.5D and 3D advanced packaging architectures, including CoWoS (Chip-on-Wafer-on-Substrate) and SoIC (System-on-Integrated-Chips) platforms. The product scope of this study primarily covers Low-CTE electronic cloth fabricated from glass fiber yarns through weaving processes, with thickness specifications ranging from ultra-thin grades (?0.03mm) to standard thicknesses, intended for AI chip packaging and related high-reliability semiconductor applications. The research object excludes standard E-glass fabrics without CTE optimization, general-purpose PCB reinforcement materials, and non-packaging applications of glass fiber textiles.

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Key Findings

Global production of Low Thermal Expansion Coefficient Electronic Cloth for AI Chip Packaging reached approximately 630,000 kilometers in 2025

The global average market price for this product stood at approximately US$890 per kilometer in 2025

Global total production capacity reached 780,000 kilometers in 2025, with an industry average gross margin of 25%

Nittobo dominates the global supply with an estimated 85-90% market share, while Chinese manufacturers are rapidly expanding capacity

Demand for Low-CTE electronic cloth is growing at a faster rate than Low-Dk electronic cloth, driven by CoWoS advanced packaging adoption

Market Trends

The Low Thermal Expansion Coefficient Electronic Cloth for AI Chip Packaging market is undergoing a profound transformation driven by the exponential growth of AI computing power and the proliferation of advanced packaging technologies. The industry is witnessing three concurrent trends reshaping the product landscape. First, product performance is being pushed to new limits, with leading manufacturers developing next-generation T-glass fabrics targeting a CTE of 2.0 ppm, representing approximately a 30% reduction from the current 2.8 ppm standard. Second, the market is experiencing a clear bifurcation toward ultra-thin specifications (?0.03mm) for high-end smartphone and edge AI applications, alongside thicker grades for AI server and data center infrastructure. Third, the industry is witnessing an accelerated transition from glass-based fabrics toward quartz-based solutions (Q-cloth), which offer superior dielectric properties and even lower thermal expansion coefficients, positioning them as the preferred material for next-generation AI platforms such as NVIDIA Rubin and 1.6T switches. This technological evolution is accompanied by a structural shift in the supply chain, as downstream customers including NVIDIA, Apple, Google, and Amazon have begun directly engaging with material suppliers to secure long-term supply agreements, bypassing traditional intermediary channels.Market Dynamics

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Drivers: The primary growth driver for the Low-CTE electronic cloth market is the explosive demand from AI chip manufacturers adopting CoWoS and other advanced packaging technologies. As AI chips increase in size and complexity, with GPU, TPU, and ASIC designs incorporating multiple chiplets and high-bandwidth memory stacks, the thermal management challenges intensify proportionally. The industry has observed that AI servers require three to five times more electronic cloth than traditional servers, with the material specification shifting from standard E-glass to Low-CTE variants. Additionally, the expanding application of Low-CTE electronic cloth in premium smartphones—particularly for applications processor substrates—has broadened the demand base beyond data center infrastructure. The deepening penetration of AI capabilities into edge devices is expected to sustain demand growth across multiple end-market segments.

Restraints: Supply-side constraints represent the most significant near-term restraint on market growth. The production of Low-CTE electronic cloth involves complex manufacturing processes, including high-temperature melting at approximately 1,300°C using expensive platinum equipment, and the drawing of glass fibers that must be thinner than human hair with zero bubbles and perfect circularity. The specialty glass formulations required for Low-CTE properties differ substantially from standard E-glass compositions, requiring dedicated melting furnaces and precise process control. Furthermore, advanced weaving looms—particularly the JAT910 model from Toyota—are essential for producing high-quality electronic cloth, and delivery lead times of 18 to 24 months have created a secondary bottleneck that constrains industry-wide capacity expansion. The limited number of qualified suppliers and the extended qualification cycles for new entrants further restrict supply responsiveness.

Opportunities: A significant market opportunity exists for manufacturers capable of qualifying as second-source suppliers to major AI chip and device manufacturers. With Nittobo's new Fukushima facility not expected to commence production until 2027, and the company's next-generation T-glass not slated for release until 2028, there is a window of opportunity for emerging suppliers to establish themselves in the supply chain. Chinese manufacturers, including Grace Fabric Technology and Sinoma Science & Technology, have already achieved technical breakthroughs and are scaling production. The market is also witnessing opportunities in product differentiation, with quartz-based fabrics (Q-cloth) representing the next frontier in performance, targeting CTE values below 2.0 ppm and superior dielectric properties for 224Gbps and higher signal transmission speeds.

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Challenges: The industry faces several significant challenges. The substantial capital investment required for new production lines—with Sinoma Science & Technology committing RMB 1.4 billion for a 35 million meter specialty fabric project and Nittobo investing ¥15 billion in its Fukushima expansion—creates high barriers to entry and financial risk for capacity expansion. Technology obsolescence risk is elevated as the industry transitions toward quartz-based solutions, potentially rendering glass-based investments less competitive. Supply chain concentration poses a systemic risk, as the industry remains highly dependent on a single dominant supplier and a limited number of specialized equipment vendors. Geopolitical tensions and trade policy uncertainty add another layer of risk, with potential impacts on cross-border supply chains and market access.Industry Chain Analysis

The industry chain for Low Thermal Expansion Coefficient Electronic Cloth for AI Chip Packaging encompasses three primary tiers. The upstream segment consists of raw material suppliers providing specialty glass formulations, including high-purity silica, alumina, and magnesium oxide, as well as auxiliary materials such as sizing agents. Key upstream considerations include the availability of high-purity quartz sand for quartz-based products and the specialized melting furnaces required for low-CTE glass fiber production. The midstream segment comprises the manufacturing of electronic-grade glass fiber yarn and the subsequent weaving into fabric. This stage involves glass melting, fiber drawing, sizing application, weaving, and heat treatment processes. The manufacturing stage is characterized by high technical barriers, significant capital intensity, and extended qualification cycles. Major global manufacturers operating in this segment include Nittobo, Grace Fabric Technology, Sinoma Science & Technology (through its Taishan Fiberglass subsidiary), Asahi Kasei, Taiwan Glass, and AGY. The downstream segment encompasses copper-clad laminate (CCL) manufacturers who impregnate the electronic cloth with resin systems to produce laminate materials, followed by IC substrate and printed circuit board (PCB) fabricators who incorporate these materials into finished substrates for AI chip packaging. The value creation within this chain is concentrated in the midstream manufacturing stage, where proprietary glass formulations and precision weaving capabilities differentiate product performance and command significant pricing premiums over standard E-glass fabrics.

Segment Insights

The Low Thermal Expansion Coefficient Electronic Cloth market can be segmented along multiple dimensions. By performance classification, the market encompasses three primary grades: Standard E-cloth, which serves as the baseline electronic fabric without CTE optimization; Low-CTE cloth (T-glass), which represents the core focus of

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this study with CTE values typically below 3 ppm/°C; and Quartz cloth (Q-cloth), which offers superior thermal and dielectric performance at a higher cost point. By thickness, products are categorized into ultra-thin (?0.03mm), medium (0.03-0.10mm), and thick (?0.10mm) grades, with ultra-thin products commanding significant technical premiums due to the difficulty of maintaining uniform fiber diameter and defect-free weaving at such minimal thicknesses. By weaving architecture, bidirectional and multidirectional fabrics serve different mechanical reinforcement requirements, with multidirectional constructions offering enhanced dimensional stability for larger chip packages. The Low-CTE segment is experiencing the most rapid growth among performance classifications, driven by the proliferation of CoWoS and other advanced packaging technologies. Within the thickness dimension, ultra-thin grades (?0.03mm) are seeing particularly strong demand from premium smartphone applications, while medium-thickness products dominate AI server and data center applications. The market is also witnessing the emergence of next-generation products, with Nittobo targeting a 2028 launch for T-glass with CTE reduced to 2.0 ppm, representing approximately a 30% improvement over current specifications.

Downstream Market Opportunities

The downstream market for Low Thermal Expansion Coefficient Electronic Cloth for AI Chip Packaging is anchored by three primary application clusters. AI data center infrastructure represents the largest and fastest-growing opportunity, with AI servers requiring three to five times the electronic cloth content of traditional servers, all of which must meet Low-CTE specifications. Within this cluster, the adoption of CoWoS and other advanced packaging technologies for GPU, TPU, and ASIC processors is the primary demand driver. High-end smartphones and consumer electronics constitute the second major application, with Low-CTE electronic cloth being used in applications processor substrates for flagship devices. The third opportunity lies in emerging applications including automotive electronics for advanced driver-assistance systems and aerospace applications requiring high-reliability packaging. The demand growth trajectory across these segments is asymmetric, with AI infrastructure applications exhibiting the steepest growth curve. The total demand for Low-CTE electronic cloth is projected to increase from approximately 670,000 meters in 2025 to 18 million meters in 2026 and exceed 33.6 million meters by 2027. This rapid demand expansion, coupled with constrained supply, is creating significant opportunities for qualified suppliers to capture market share and establish long-term customer relationships.

Regional Insights

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The Asia-Pacific region dominates the global market for Low Thermal Expansion Coefficient Electronic Cloth for AI Chip Packaging, accounting for the majority of global production capacity and consumption. Japan maintains its position as the technology leader and primary supply source, with Nittobo controlling an estimated 85-90% of the global T-glass market. The company's production base in Fukushima and its Taiwan-based Nittobo Asia Glass Fiber operations constitute the industry's most significant manufacturing footprint. China has emerged as the most dynamic regional market, with multiple domestic manufacturers achieving technical breakthroughs and scaling production capabilities. Grace Fabric Technology has established itself as the world's second-largest T-glass supplier and the only Chinese manufacturer capable of mass-producing ultra-thin T-glass. Sinoma Science & Technology, through its Taishan Fiberglass subsidiary, has invested significantly in Low-CTE production capacity, positioning itself as a comprehensive specialty fabric supplier. Taiwan serves as a critical production hub, hosting Nittobo's Asian manufacturing operations and Taiwan Glass's Low-CTE production lines. The North American and European markets are primarily consumption centers, with limited domestic production capacity, making them dependent on Asian supply sources. The regional competitive dynamics are characterized by Japanese technological leadership, rapid Chinese capacity expansion, and a structural supply-demand imbalance that is expected to persist through 2027.

Competitive Landscape Analysis

The competitive landscape for Low Thermal Expansion Coefficient Electronic Cloth for AI Chip Packaging is characterized by extreme concentration, with a single dominant supplier and a small number of emerging challengers. Nittobo holds an estimated 85-90% share of the global T-glass market, a position built on decades of proprietary glass formulation expertise and precision manufacturing capabilities. The company's T-glass has become the de facto industry standard, with major AI chip manufacturers specifying Nittobo as the preferred or exclusive supplier. Grace Fabric Technology has emerged as the world's second-largest T-glass supplier and the leading Chinese manufacturer in this segment, with its ultra-thin T-glass products having received certification from major downstream customers and entering volume production in 2025. Sinoma Science & Technology, through its Taishan Fiberglass subsidiary, has established itself as a comprehensive specialty electronic fabric supplier with Low-CTE production capabilities, backed by significant capital investment in new production lines. Other notable competitors include Taiwan Glass, which has been actively developing Low-CTE production capacity; Asahi Kasei, which supplies low-dielectric materials and is developing quartz-based cloth; and AGY, which has partnered with JPS Composite

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Materials on domestic Low-CTE glass fiber fabric production. Emerging Chinese manufacturers including Guangyuan New Materials and International Composites are investing heavily in Low-CTE capacity, with Guangyuan having commissioned its Low-CTE production line in October 2025. The competitive dynamics are expected to evolve significantly as new capacity comes online, with the supply-demand imbalance creating opportunities for second-source qualification and market share gains among capable suppliers.

Report Scope

This report studies the global Low Thermal Expansion Coefficient Electronic Cloth for AI Chip Packaging production, demand, key manufacturers, and key regions.

This report is a detailed and comprehensive analysis of the world market for Low Thermal Expansion Coefficient Electronic Cloth for AI Chip Packaging and provides market size (US$ million) and Year-over-Year (YoY) Growth, considering 2025 as the base year. This report explores demand trends and competition, as well as details the characteristics of Low Thermal Expansion Coefficient Electronic Cloth for AI Chip Packaging that contribute to its increasing demand across many markets.

Highlights and key features of the study

Global Low Thermal Expansion Coefficient Electronic Cloth for AI Chip Packaging total production and demand, 2021-2032, (K Meter)

Global Low Thermal Expansion Coefficient Electronic Cloth for AI Chip Packaging total production value, 2021-2032, (USD Million)

Global Low Thermal Expansion Coefficient Electronic Cloth for AI Chip Packaging production by region & country, production, value, CAGR, 2021-2032, (USD Million) & (K Meter), (based on production site)

Global Low Thermal Expansion Coefficient Electronic Cloth for AI Chip Packaging consumption by region & country, CAGR, 2021-2032 & (K Meter)

U.S. VS China: Low Thermal Expansion Coefficient Electronic Cloth for AI Chip Packaging domestic production, consumption, key domestic manufacturers and

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share

Global Low Thermal Expansion Coefficient Electronic Cloth for AI Chip Packaging production by manufacturer, production, price, value and market share 2021-2026, (USD Million) & (K Meter)

Global Low Thermal Expansion Coefficient Electronic Cloth for AI Chip Packaging production by Type, production, value, CAGR, 2021-2032, (USD Million) & (K Meter)

Global Low Thermal Expansion Coefficient Electronic Cloth for AI Chip Packaging production by Application, production, value, CAGR, 2021-2032, (USD Million) & (K Meter)

This report profiles key players in the global Low Thermal Expansion Coefficient Electronic Cloth for AI Chip Packaging market based on the following parameters - company overview, production, value, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include Nittobo, Sinoma Science & Technology, Grace Fabric Technology Co.,Ltd., Feilihua, Asahi Kasei, Unitika Ltd., Changhai Co., Ltd., Taiwan Glass Group, AGY, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Stakeholders would have ease in decision-making through various strategy matrices used in analyzing the World Low Thermal Expansion Coefficient Electronic Cloth for AI Chip Packaging market

Detailed Segmentation:

Each section contains quantitative market data including market by value (US$ Millions), volume (production, consumption) & (K Meter) and average price (US$/K Meter) by manufacturer, by Type, and by Application. Data is given for the years 2021-2032 by year with 2025 as the base year, 2026 as the estimate year, and 2027-2032 as the forecast year.

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Global Low Thermal Expansion Coefficient Electronic Cloth for AI Chip Packaging Market, By Region:

United States

China

Europe

Japan

South Korea

ASEAN

India

Rest of World

Market Segmentation

Global Low Thermal Expansion Coefficient Electronic Cloth for AI Chip Packaging Market, Segmentation by Type:

Standard E-cloth

Low-CTE Cloth

Quartz Cloth

Global Low Thermal Expansion Coefficient Electronic Cloth for AI Chip Packaging Market, Segmentation by Thickness:

<0.03mm

0.03-0.10mm

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>0.10mm

Global Low Thermal Expansion Coefficient Electronic Cloth for AI Chip Packaging Market, Segmentation by Fabric Weave:

Bidirectional

Multidirectional

Global Low Thermal Expansion Coefficient Electronic Cloth for AI Chip Packaging Market, Segmentation by Application:

Electronics and Semiconductors

Aerospace

Sports Equipment

Others

Companies Profiled:

Nittobo

Sinoma Science & Technology

Grace Fabric Technology Co.,Ltd.

Feilihua

Asahi Kasei

Unitika Ltd.

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Changhai Co., Ltd.

Taiwan Glass Group

AGY

Key Questions Answered

1. How big is the global Low Thermal Expansion Coefficient Electronic Cloth for AI Chip Packaging market?
2. What is the demand of the global Low Thermal Expansion Coefficient Electronic Cloth for AI Chip Packaging market?
3. What is the year over year growth of the global Low Thermal Expansion Coefficient Electronic Cloth for AI Chip Packaging market?
4. What is the total value of the global Low Thermal Expansion Coefficient Electronic Cloth for AI Chip Packaging market?
5. Who are the Major Players in the global Low Thermal Expansion Coefficient Electronic Cloth for AI Chip Packaging market?
6. What are the growth factors driving the market demand?

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